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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I ² C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c64a-04e-l

PIC16C6X

TABLE 3-1: PIC16C61 PINOUT DESCRIPTION

Pin Name	DIP Pin#	SOIC Pin#	Pin Type	Buffer Type	Description
OSC1/CLKIN	16	16	I	ST/CMOS ⁽¹⁾	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/VPP	4	4	I/P	ST	Master clear reset input or programming voltage input. This pin is an active low reset to the device.
RA0	17	17	I/O	TTL	PORTA is a bi-directional I/O port. RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
RA1	18	18	I/O	TTL	
RA2	1	1	I/O	TTL	
RA3	2	2	I/O	TTL	
RA4/T0CKI	3	3	I/O	ST	
RB0/INT	6	6	I/O	TTL/ST ⁽²⁾	PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs. RB0 can also be the external interrupt pin. Interrupt on change pin. Interrupt on change pin. Interrupt on change pin. Serial programming clock. Interrupt on change pin. Serial programming data.
RB1	7	7	I/O	TTL	
RB2	8	8	I/O	TTL	
RB3	9	9	I/O	TTL	
RB4	10	10	I/O	TTL	
RB5	11	11	I/O	TTL	
RB6	12	12	I/O	TTL/ST ⁽³⁾	
RB7	13	13	I/O	TTL/ST ⁽³⁾	
VSS	5	5	P	—	Ground reference for logic and I/O pins.
VDD	14	14	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = output I/O = input/output P = power
 — = Not used TTL = TTL input ST = Schmitt Trigger input

- Note 1: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.
 Note 2: This buffer is a Schmitt Trigger input when configured as the external interrupt.
 Note 3: This buffer is a Schmitt Trigger input when used in serial programming mode.

PIC16C6X

FIGURE 7-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

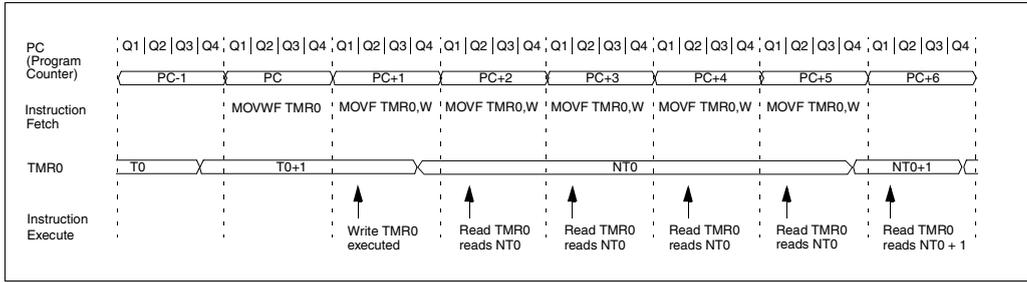
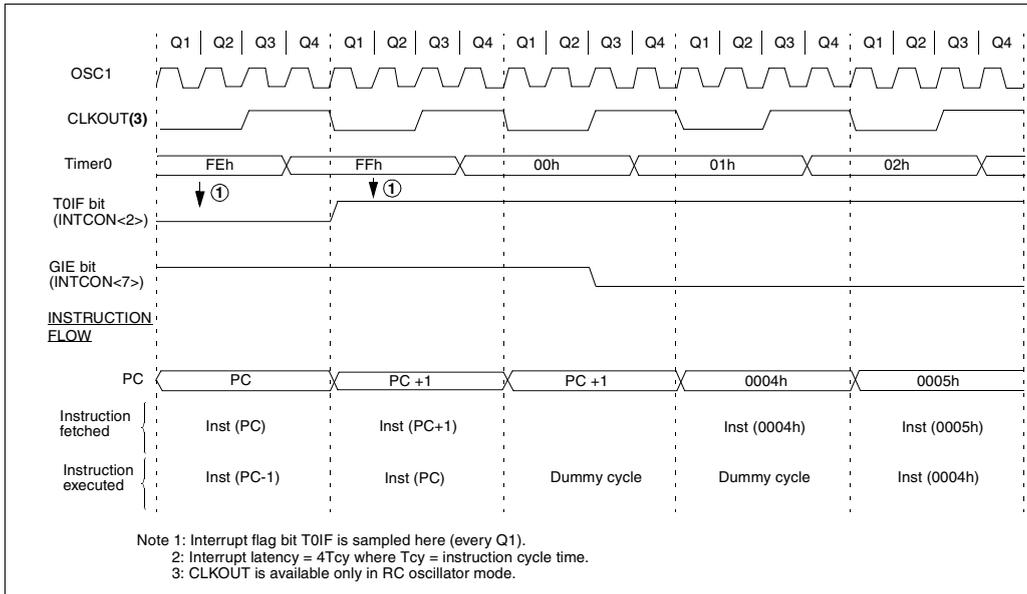


FIGURE 7-4: TMR0 INTERRUPT TIMING



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FIGURE 12-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER (ADDRESS 18h)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D
bit7							bit0

R = Readable bit
 W = Writable bit
 U = Unimplemented bit, read as '0'
 - n = Value at POR reset
 x = unknown

bit 7: **SPEN**: Serial Port Enable bit
 (Configures RC7/RX/DT and RC6/TX/CK pins as serial port pins when bits TRISC<7:6> are set)
 1 = Serial port enabled
 0 = Serial port disabled

bit 6: **RX9**: 9-bit Receive Enable bit
 1 = Selects 9-bit reception
 0 = Selects 8-bit reception

bit 5: **SREN**: Single Receive Enable bit
Asynchronous mode
 Don't care

Synchronous mode - master
 1 = Enables single receive
 0 = Disables single receive
 This bit is cleared after reception is complete.

Synchronous mode - slave
 Unused in this mode

bit 4: **CREN**: Continuous Receive Enable bit
Asynchronous mode
 1 = Enables continuous receive
 0 = Disables continuous receive

Synchronous mode
 1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
 0 = Disables continuous receive

bit 3: **Unimplemented**: Read as '0'

bit 2: **FERR**: Framing Error bit
 1 = Framing error (Can be updated by reading RCREG register and receive next valid byte)
 0 = No framing error

bit 1: **OERR**: Overrun Error bit
 1 = Overrun error (Can be cleared by clearing bit CREN)
 0 = No overrun error

bit 0: **RX9D**: 9th bit of received data (Can be parity bit)

13.2 Oscillator Configurations

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

13.2.1 OSCILLATOR TYPES

The PIC16CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

13.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In LP, XT, or HS modes a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 13-4). The PIC16CXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in LP, XT, or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 13-5).

FIGURE 13-4: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)

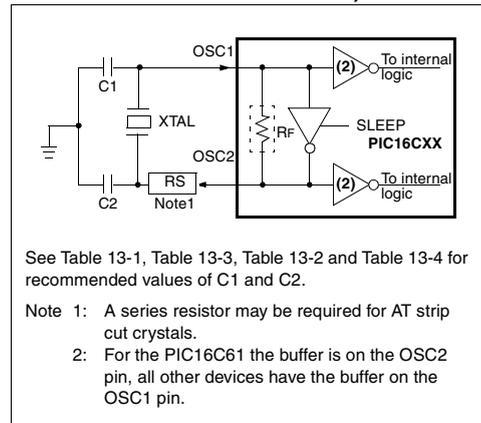
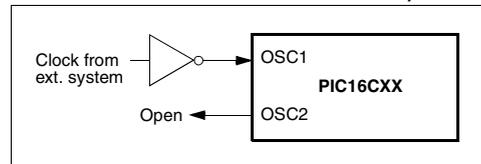


FIGURE 13-5: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)



PIC16C6X

13.3 Reset

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The PIC16CXX differentiates between various kinds of reset:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ reset during normal operation
- $\overline{\text{MCLR}}$ reset during SLEEP
- WDT Reset (normal operation)
- Brown-out Reset (BOR) - Not on PIC16C61/62/64/65

Some registers are not affected in any reset condition, their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a “reset state” on Power-on Reset (POR), on $\overline{\text{MCLR}}$ or WDT Reset, on $\overline{\text{MCLR}}$ reset during SLEEP, and on Brown-out Reset (BOR). They are not affected by a WDT Wake-up, which is viewed as the resumption of normal operation.

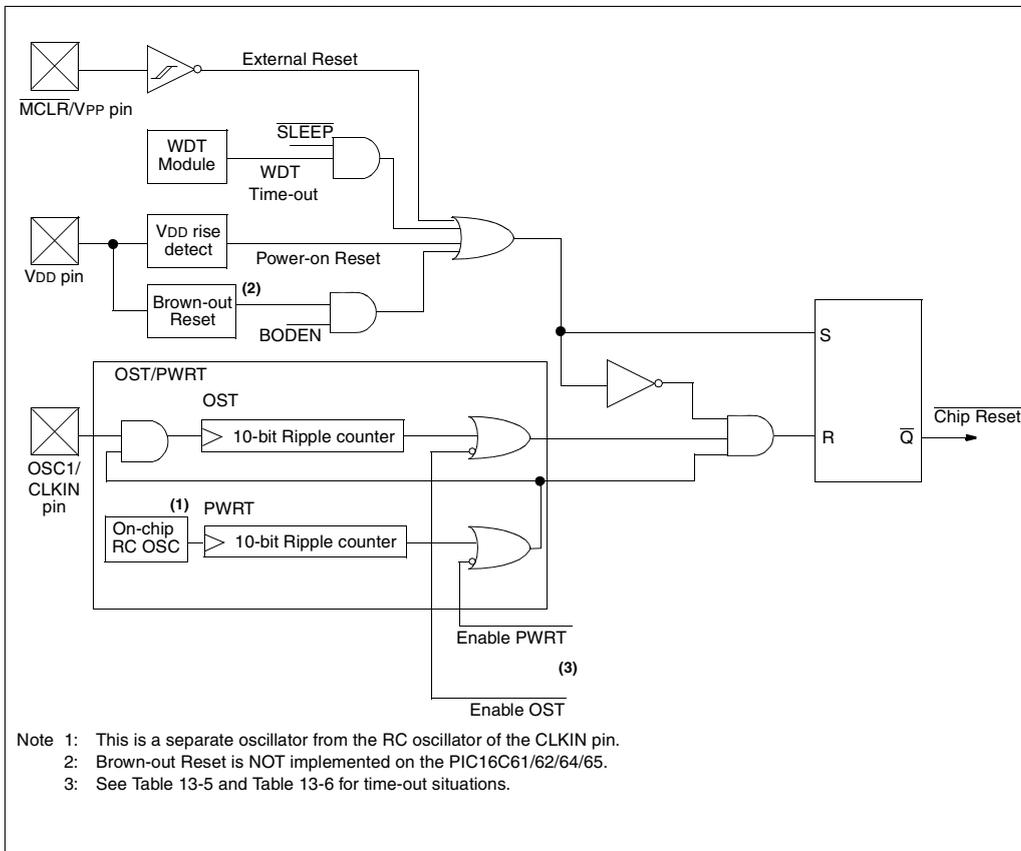
The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different reset situations as indicated in Table 13-7, Table 13-8, and Table 13-9. These bits are used in software to determine the nature of the reset. See Table 13-12 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 13-9.

On the PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67, the $\overline{\text{MCLR}}$ reset path has a noise filter to detect and ignore small pulses. See parameter #34 for pulse width specifications.

It should be noted that a WDT Reset does not drive the $\overline{\text{MCLR}}$ pin low.

FIGURE 13-9: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



PIC16C6X

TABLE 13-12: INITIALIZATION CONDITIONS FOR ALL REGISTERS

Register	Applicable Devices													Power-on Reset Brown-out Reset	MCLR Reset during: – normal operation – SLEEP WDT Reset	Wake-up via interrupt or WDT Wake-up	
W	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	N/A	N/A	N/A
TMR0	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000h	0000h	PC + 1 ⁽²⁾
STATUS	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0001 1xxx	000q quuu ⁽³⁾	uuuq quuu ⁽³⁾
FSR	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	--x xxxx	---u uuuu	---u uuuu
	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	--xx xxxx	--uu uuuu	--uu uuuu
PORTB	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTD	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTE	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	---- -xxx	---- -uuu	---- -uuu
PCLATH	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	---0 0000	---0 0000	---u uuuu
INTCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 000x	0000 000u	uuuu uuuu ⁽¹⁾
PIR1	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	00-- 0000	00-- 0000	uu-- uuuu ⁽¹⁾
	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu ⁽¹⁾
PIR2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	---- --0	---- --0	---- --u ⁽²⁾
TMR1L	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	--00 0000	--uu uuuu	--uu uuuu
TMR2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu
T2CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	-000 0000	-000 0000	-uuu uuuu
SSPBUF	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
SSPCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu
CCPR1L	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1H	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	--00 0000	--00 0000	--uu uuuu
RCSTA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 -00x	0000 -00x	uuuu -uuu
TXREG	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu
RCREG	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu
CCPR2L	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR2H	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu
OPTION	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111 1111	1111 1111	uuuu uuuu
TRISA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	--1 1111	--1 1111	--u uuuu
	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	--11 1111	--11 1111	--uu uuuu
TRISB	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111 1111	1111 1111	uuuu uuuu
TRISC	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111 1111	1111 1111	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0', q = value depends on condition.

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

3: See Table 13-10 and Table 13-11 for reset value for specific conditions.

PIC16C6X

FIGURE 13-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 1

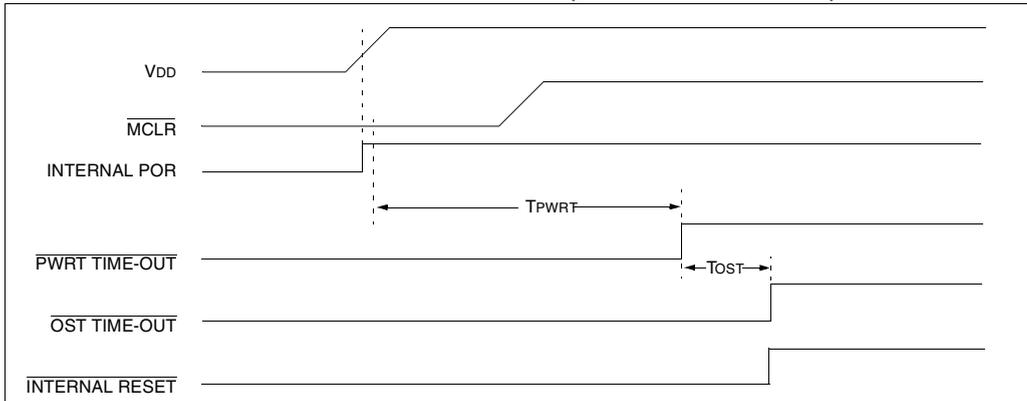


FIGURE 13-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 2

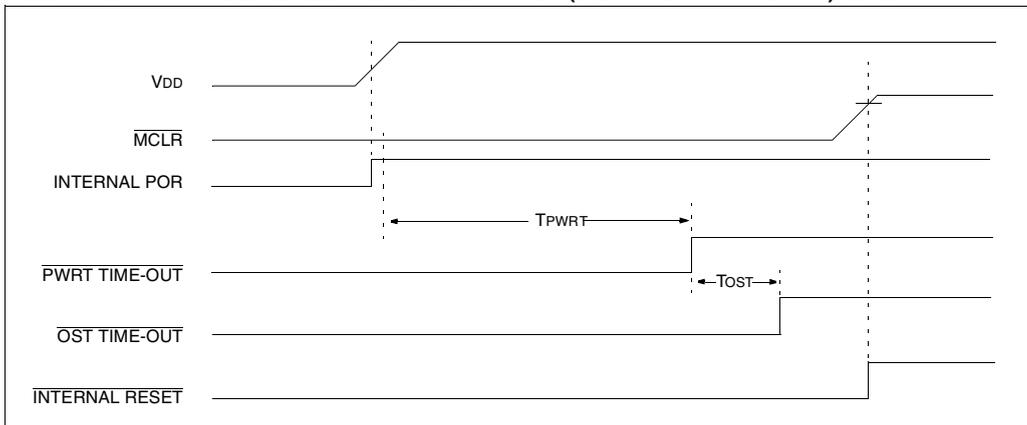
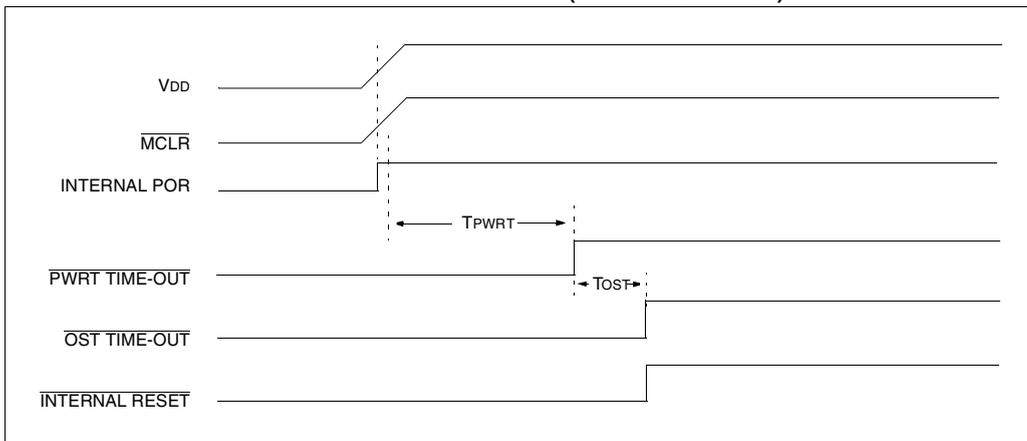


FIGURE 13-13: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO V_{DD})



PIC16C6X

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
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NOTES:

PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

17.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I²C specifications only)
4. Ts (I²C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	\overline{RD}
cs	\overline{CS}	rw	\overline{RD} or \overline{WR}
di	SDI	sc	SCK
do	SDO	ss	\overline{SS}
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	\overline{MCLR}	wr	\overline{WR}

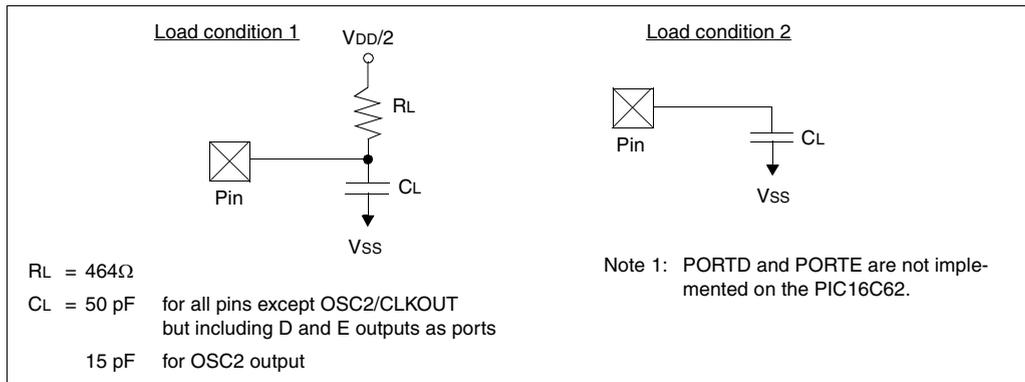
Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I²C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I²C specifications only)

CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		

FIGURE 17-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



17.5 Timing Diagrams and Specifications

FIGURE 17-2: EXTERNAL CLOCK TIMING

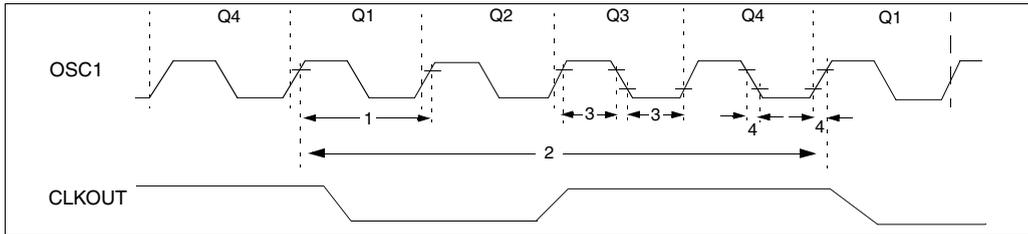


TABLE 17-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	1,000	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200	TCY	DC	ns	TCY = 4/Fosc
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 18-9: SPI MODE TIMING

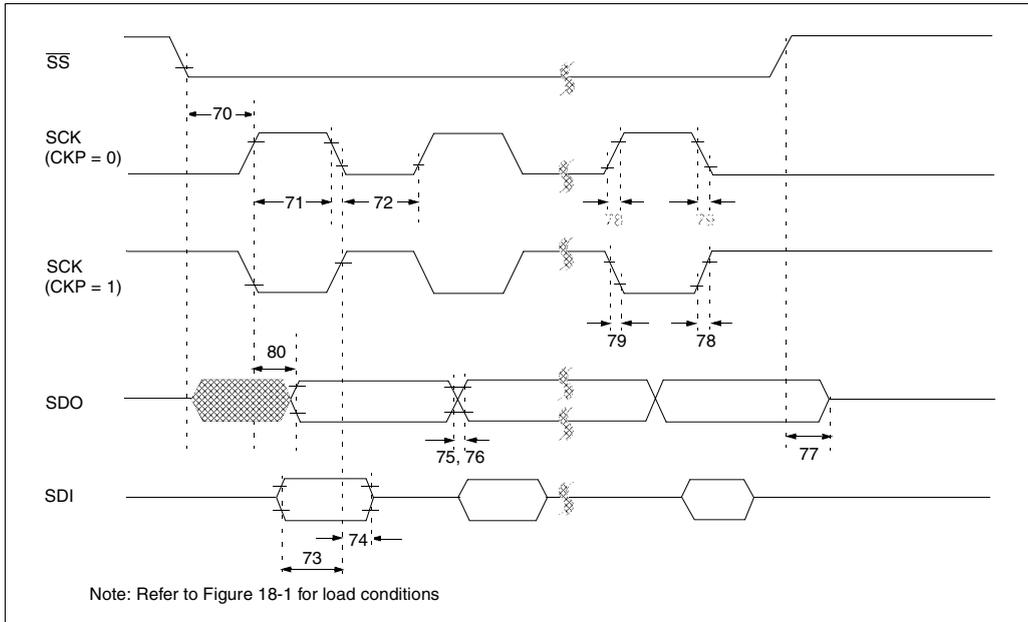


TABLE 18-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	\overline{SS} ↓ to SCK↓ or SCK↑ input	T _{CY}	—	—	ns	
71*	TscH	SCK input high time (slave mode)	T _{CY} + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	T _{CY} + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	Tsch2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	\overline{SS} ↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	Tsch2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 19-11: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

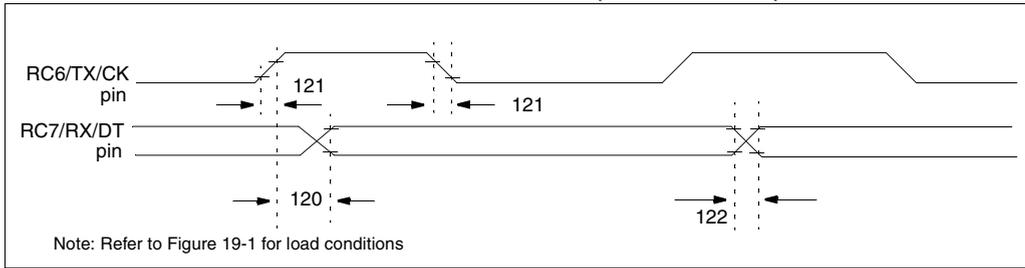


TABLE 19-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
120	TckH2dV	SYNC XMIT (MASTER & SLAVE)			80	ns		
		Clock high to data out valid	PIC16C65	—	—	100	ns	
121	Tckrf	Clock out rise time and fall time (Master Mode)	PIC16C65	—	—	45	ns	
			PIC16LC65	—	—	50	ns	
122	Tdtfr	Data out rise time and fall time	PIC16C65	—	—	45	ns	
			PIC16LC65	—	—	50	ns	

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 19-12: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

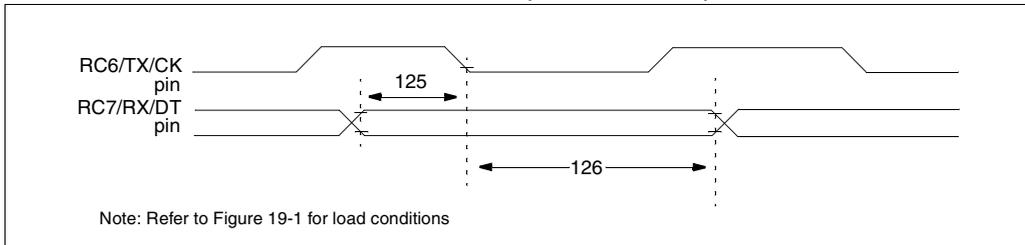


TABLE 19-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE)					
		Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 20-10: I²C BUS START/STOP BITS TIMING

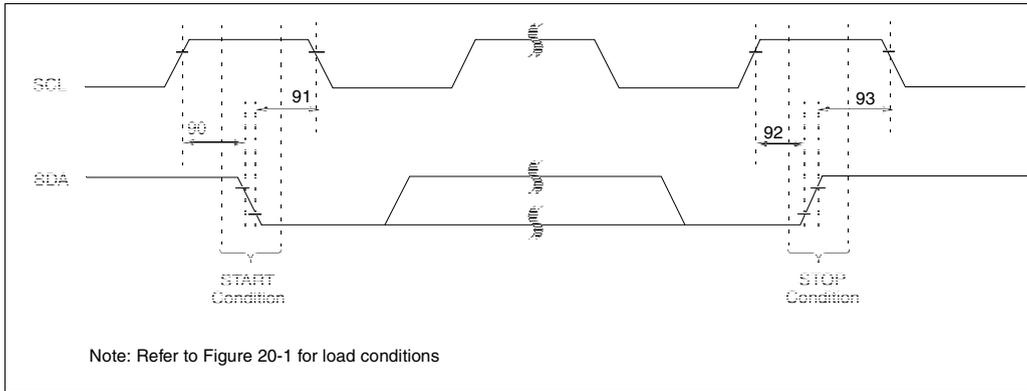


TABLE 20-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions	
90*	TSU:STA	START condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
		400 kHz mode	600	—	—			
91*	THD:STA	START condition Hold time	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
		400 kHz mode	600	—	—			
92*	TSU:STO	STOP condition Setup time	100 kHz mode	4700	—	—	ns	
		400 kHz mode	600	—	—			
93	THD:STO	STOP condition Hold time	100 kHz mode	4000	—	—	ns	
		400 kHz mode	600	—	—			

* These parameters are characterized but not tested.

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FIGURE 21-8: PARALLEL SLAVE PORT TIMING (PIC16CR65)

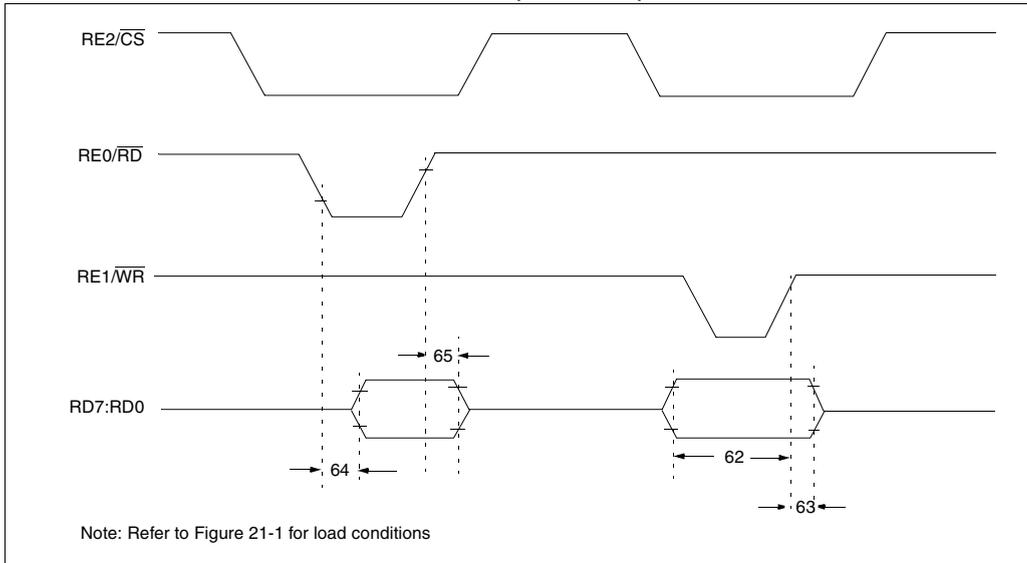


TABLE 21-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16CR65)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
62*	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setup time)	20	—	—	ns		
63*	TwrH2dtI	$\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ to data-in invalid (hold time)	PIC16CR65	20	—	—	ns	
			PIC16LCR65	35	—	—	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data-out valid	—	—	80	ns		
65*	TrdH2dtI	$\overline{RD}\uparrow$ or $\overline{CS}\uparrow$ to data-out invalid	10	—	30	ns		

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

DC CHARACTERISTICS							
Standard Operating Conditions (unless otherwise stated)							
Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial							
Operating voltage VDD range as described in DC spec Section 22.1 and Section 22.2							
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
Output High Voltage							
D090	I/O ports (Note 3)	VOH	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D090A			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°C to +125°C
D150*	Open-Drain High Voltage	VOD	-	-	14	V	RA4 pin
Capacitive Loading Specs on Output Pins							
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	CIO	-	-	50	pF	
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

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FIGURE 22-8: PARALLEL SLAVE PORT TIMING (PIC16C67)

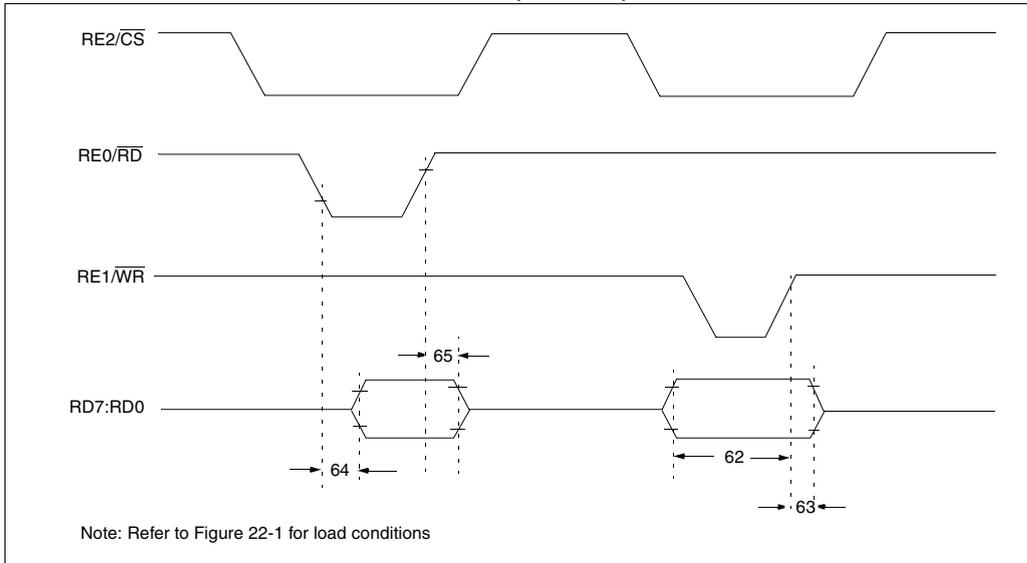


TABLE 22-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C67)

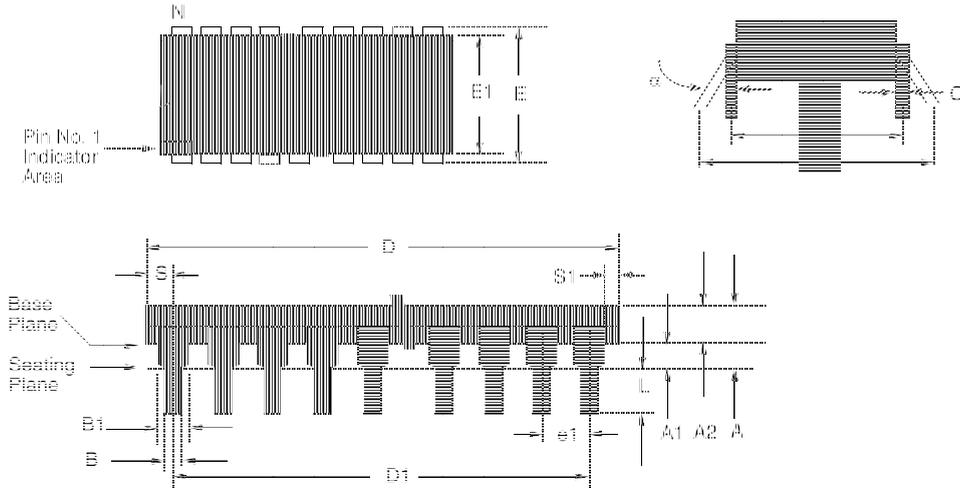
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
62*	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setup time)	20	—	—	ns	Extended Range Only	
			25	—	—	ns		
63*	TwrH2dtl	$\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ to data-in invalid (hold time)	PIC16C67	20	—	—	ns	
			PIC16LC67	35	—	—	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data-out valid	—	—	80	ns	Extended Range Only	
			—	—	90	ns		
65*	TrdH2dtl	$\overline{RD}\uparrow$ or $\overline{CS}\uparrow$ to data-out invalid	10	—	30	ns		

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

24.3 40-Lead Plastic Dual In-line (600 mil) (P)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

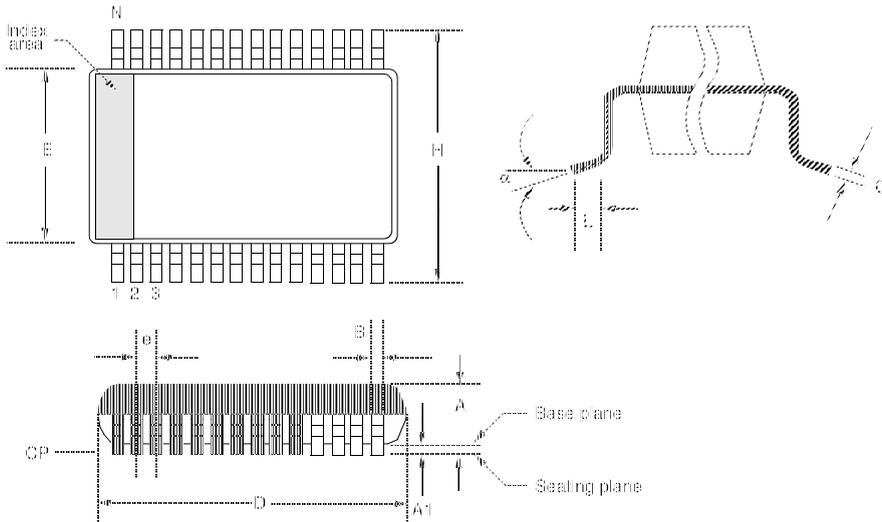


Package Group: Plastic Dual In-Line (PLA)						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	–	5.080		–	0.200	
A1	0.381	–		0.015	–	
A2	3.175	4.064		0.125	0.160	
B	0.355	0.559		0.014	0.022	
B1	1.270	1.778	Typical	0.050	0.070	Typical
C	0.203	0.381	Typical	0.008	0.015	Typical
D	51.181	52.197		2.015	2.055	
D1	48.260	48.260	Reference	1.900	1.900	Reference
E	15.240	15.875		0.600	0.625	
E1	13.462	13.970		0.530	0.550	
e1	2.489	2.591	Typical	0.098	0.102	Typical
eA	15.240	15.240	Reference	0.600	0.600	Reference
eB	15.240	17.272		0.600	0.680	
L	2.921	3.683		0.115	0.145	
N	40	40		40	40	
S	1.270	–		0.050	–	
S1	0.508	–		0.020	–	

PIC16C6X

24.10 28-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Package Group: Plastic SSOP						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	1.730	1.990		0.068	0.078	
A1	0.050	0.210		0.002	0.008	
B	0.250	0.380		0.010	0.015	
C	0.130	0.220		0.005	0.009	
D	10.070	10.330		0.396	0.407	
E	5.200	5.380		0.205	0.212	
e	0.650	0.650	Reference	0.026	0.026	Reference
H	7.650	7.900		0.301	0.311	
L	0.550	0.950		0.022	0.037	
N	28	28		28	28	
CP	-	0.102		-	0.004	

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